

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

E·XFI

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	64MHz
Connectivity	I ² C, IrDA, LINbus, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, HLVD, LCD, POR, PWM, WDT
Number of I/O	86
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 24x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18f96j94-i-pf

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

80-Pin TQFP Comparator PPS-Lite⁽¹⁾ Pull-up Interrupt MSSP REFO Basic HLVD ADC CTMU EMB USB LCD PSP 0 RA0 AN0/ SEG19 RP0 30 AN1-RA1 29 AN1 SEG18 RP1 _ _ ____ _ _ ____ _ _ _ _ _ RA2 28 AN2/ ____ _ _ _ SEG21 _ _ ____ ____ RP2 _ _ VRFF-RA3 27 RP3 AN3/ _ _ _ _ _ _ ____ _ _ _ VREF+ SEG14 RP4 RA4 34 AN6 _ _ _ _ _ _ _ _ _ _ _ RA5 33 AN4 C1INA/ LVDIN SEG15 RP5 _ _ _ _ ____ _ _ _ _ C2INA C3INA RA6 50 RP6 OSC2/ CLKO **RP10** OSC1/ RA7 49 _ _ _ _ _ _ _ _ _ _ CLKI RB0 58 _ _ _ CTED13 _ VLCAP1 _ ____ INT0 _ _ RP8 _ _ RB1 VLCAP2 57 RP9 RB2 CTED1 SEG9 RP14 56 _ RB3 55 _ _ CTED2 _ SEG10 _ _ _ _ RP7 _ _ _ _ RB4 54 _ _ CTED3 _ SEG11 _ **RP12** _ _ _ _ _ RB5 53 CTED4 SEG8 **RP13** _ _ _ RB6 52 CTED5 PGC _ _ ____ -____ _ ____ RB7 47 CTED6 PGD _ _ _ _ _ ____ ____ ____ _ SOSCO/ RC0 36 _ ____ _ _ ____ _ ____ _ SCKI/ PWRCLK RC1 35 SOSCI RC2 43 AN9 CTED7 SEG13 **RP11** _ ____ _ _ ____ _ ____ ____ _ _ RC3 44 CTED8 SEG17 SCL1 RP15 _ ____ _ _ ____ ____ ____ ____ _ _ RC4 45 CTED9 SDA1 _ **RP17** _ SEG16 ____ RC5 46 CTED10 SEG12 RP16 _ _ _ ____ _ UOE RC6 37 CTED11 SEG27 **RP18** _ _ ____ _ ____ _ ____ _ _ _ RC7 38 ____ CTED12 SEG22 **RP19** _ _ _ _ _ _ RD0 PSP0 AD0 Υ 72 SEG0 **RP20** RD1 SEG1 PSP1 AD1 RP21 69 Y _ _ _ _ _ _ _ — ____ RD2 68 _ _ _ _ _ SEG2 _ PSP2 _ _ AD2 RP22 Υ _ RD3 SEG3 PSP3 AD3 RP23 Y 67 RD4 66 SEG4 PSP4 AD4 RP24 Υ RD5 SEG5 PSP5 RP25 65 SDA2 AD5 Υ _ _ _ _ _ ____ _ _ RD6 64 _ _ _ SEG6 SCL2 PSP6 _ AD6 RP26 Υ _ _ _ Y RD7 PSP7 REFO2 63 _ _ _ _ SEG7 _ AD7 RP27 RE0 4 LCDBIAS1 RD AD8 **RP28** Y WR RE1 3 ____ _ _ _ _ LCDBIAS2 _ ____ _ AD9 **RP29** Υ _ RE2 78 _ _ _ _ LCDBIAS3 _ CS ____ AD10 **RP30** Y _ _ RE3 77 COM0 REF01 AD11 RP33 Υ RE4 COM1 AD12 **RP32** 76 Y _ _ _ ____ _ _ ____ ____ _ ____ RE5 75 COM2 AD13 **RP37** Υ _ ____ _ _ _ _ ____ _ ____ _ RE6 74 AD14 Y COM3 RP34 _ _ _ RE7 73 LCDBIAS0 AD15 RP31 Υ

SEG20

_

TABLE 3:80-PIN ALLOCATION TABLE (PIC18F8XJ94)

18

AN7

C2INB

CTMUI

RF2

Υ

_

RP36

ture and low VDD both have a limiting effect on the loop gain, such that if the circuit functions at these extremes, the designer can be more assured of proper operation at other temperatures and supply voltage combinations. The output sine wave should not be clipped in the highest gain environment (highest VDD and lowest temperature) and the sine output amplitude should be large enough in the lowest gain environment (lowest VDD and highest temperature) to cover the logic input requirements of the clock, as listed in the device data sheet. OSC1 may have specified VIL and VIH levels (refer to the specific product data sheet for more information).

A method for improving start-up is to use a value of C2 greater than C1. This causes a greater phase shift across the crystal at power-up, which speeds oscillator start-up. Besides loading the crystal for proper frequency response, these capacitors can have the effect of lower-ing loop gain if their value is increased. C2 can be selected to affect the overall gain of the circuit. A higher C2 can lower the gain if the crystal is being overdriven (also see discussion on Rs). Capacitance values that are too high can store and dump too much current through the crystal, so C1 and C2 should not become excessively large. Unfortunately, measuring the wattage through a crystal is difficult, but if you do not stray too far from the suggested values, you should not have to be concerned with this.

A series resistor, Rs, is added to the circuit if after all other external components are selected to satisfaction, and the crystal is still being overdriven. This can be determined by looking at the OSC2 pin, which is the driven pin, with an oscilloscope. Connecting the probe to the OSC1 pin will load the pin too much and negatively affect performance. Remember that a scope probe adds its own capacitance to the circuit, so this may have to be accounted for in your design (i.e., if the circuit worked best with a C2 of 22 pF and the scope probe was 10 pF, a 33 pF capacitor may actually be called for). The output signal should not be clipping or flattened. Overdriving the crystal can also lead to the circuit jumping to a higher harmonic level, or even, crystal damage.

The OSC2 signal should be a clean sine wave that easily spans the input minimum and maximum of the clock input pin. An easy way to set this is to again test the circuit at the minimum temperature and maximum VDD that the design will be expected to perform in; then, look at the output. This should be the maximum amplitude of the clock output. If there is clipping, or the sine wave is distorted near VDD and Vss, increasing load capacitors may cause too much current to flow through the crystal, or push the value too far from the manufacturer's load specification. To adjust the crystal current, add a trimmer potentiometer between the crystal inverter output pin and C2, and adjust it until the sine wave is clean. The crystal will experience the highest drive currents at the low temperature and high VDD extremes.

The trimmer potentiometer should be adjusted at these limits to prevent overdriving. A series resistor, Rs, of the closest standard value can now be inserted in place of the trimmer. If Rs is too high, perhaps more than 20 k Ω , the input will be too isolated from the output, making the clock more susceptible to noise. If you find a value this high is needed to prevent overdriving the crystal, try increasing C2 to compensate or changing the oscillator operating mode. Try to get a combination where Rs is around 10 k Ω or less, and load capacitance is not too far from the manufacturer's specification.

3.7 External Clock Input

In EC mode, the OSC1 pin is in a high-impedance state and can be driven by CMOS drivers. The OSC2 pin can be configured as either an I/O or the clock output (Fosc 4) by selecting the CLKOEN bit (CONFIG2L<5>). With CLKOEN set (Figure 3-5), the clock output is available for testing or synchronization purposes. With CLKOEN clear (Figure 3-6), the OSC2 pin becomes a general purpose I/O pin. The feedback device between OSC1 and OSC2 is turned off to save current.

FIGURE 3-5: EXTERNAL CLOCK INPUT OPERATION (CLKOEN = 1)



FIGURE 3-6: EXTERNAL CLOCK INPUT OPERATION (CLKOEN = 0)



TABL	_E 6-2:	REGISTER	FILE SUN	MARY (C	CONTINUED))			
	File Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
F03h	SSP2BUF	MSSP2 Receive	e Buffer/Transmi	t Register					
F02h	SSP2ADD	MSSP2 Address	s Register in I ² C	Slave Mode. M	SSP1 Baud Rate	Reload Register in	² C Master Mode.		
F01h	ANCFG	_	_	_	_	_	VBG6EN	VBG2EN	VBGEN
F00h	DMACON2	DLYCYC3	DLYCYC2	DLYCYC1	DLYCYC0	INTLVL3	INTLVL2	INTLVL1	INTLVL0
EFFh	RCSTA4	SPEN	RX9	SREN	CREN	ADDEN	FERR	OERR	RX9D
EFEh	TXSTA4	CSRC	TX9	TXEN	SYNC	SENDB	BRGH	TRMT	TX9D
EFDh	BAUDCON4	ABDOVF	RCIDL	RXDTP	TXCKP	BRG16	IREN	WUE	ABDEN
EFCh	SPBRGH4	EUSART4 Bau	d Rate Generato	r High Byte					
EFBh	SPBRG4	EUSART4 Bau	d Rate Generato	r					
EFAh	RCREG4	EUSART4 Rece	eive Data FIFO						
EF9h	TXREG4	EUSART4 Tran	smit Data FIFO						
EF8h	CTMUCON1	CTMUEN	_	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN	TRIGEN
EF7h	CTMUCON2	ITRIM5	ITRIM4	ITRIM3	ITRIM2	ITRIM1	ITRIM0	IRNG1	IRNG0
EF6h	CTMUCON3	EDG2EN	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	_	_
EF5h	CTMUCON4	EDG1EN	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
EF4h	PMD0	CCP10MD	CCP9MD	CCP8MD	CCP7MD	CCP6MD	CCP5MD	CCP4MD	ECCP3MD
EF3h	PMD1	ECCP2MD	ECCP1MD	UART4MD	UART3MD	UART2MD	UART1MD	SSP2MD	SSP1MD
EF2h	PMD2	TMR8MD	TMR6MD	TMR5MD	TMR4MD	TMR3MD	TMR2MD	TMR1MD	TMR0MD
EF1h	PMD3	DSMMD	CTMUMD	ADCMD	RTCCMD	LCDMD	PSPMD	REFO1MD	REFO2MD
EF0h	PMD4	CMP1MD	CMP2MD	CMP3MD	USBMD	IOCMD	LVDMD	_	EMBMD
EEFh	MDCON	MDEN	MDOE	MDSLR	MDOPOL	MDO	—	_	MDBIT
EEEh	MDSRC	MDSODIS	_	_	_	MDSRC3	MDSRC2	MDSRC1	MDSRC0
EEDh	MDCARH	MDCHODIS	MDCHPOL	MDCHSYNC	_	MDCH3	MDCH2	MDCH1	MDCH0
EECh	MDCARL	MDCLODIS	MDCLPOL	MDCLSYNC	_	MDCL3	MDCL2	MDCL1	MDCL0
EEBh	ODCON1	ECCP2OD	ECCP10D	USART4OD	USART3OD	USART2OD	USART10D	SSP2OD	SSP10D
EEAh	ODCON2	CCP10OD	CCP90D	CCP8OD	CCP7OD	CCP6OD	CCP5OD	CCP4OD	ECCP3OD
EE9h	TRISK	TRISK7	TRISK6	TRISK5	TRISK4	TRISK3	TRISK2	TRISK1	TRISK0
EE8h	LATK	LATK7	LATK6	LATK5	LATK4	LATK3	LATK2	LATK1	LATK0
EE7h	PORTK	RK7	RK6	RK5	RK4	RK3	RK2	RK1	RK0
EE6h	TRISL	TRISL7	TRISL6	TRISL5	TRISL4	TRISL3	TRISL2	TRISL1	TRISL0
EE5h	LATL	LATL7	LATL6	LATL5	LATL4	LATL3	LATL2	LATL1	LATL0
EE4h	PORTL	RL7	RL6	RL5	RL4	RL3	RL2	RL1	RL0
EE3h	MEMCON	EBDIS	_	WAIT1	WAIT0	—	—	WM1	WM0
EE2h	REFO1CON	ON	_	SIDL	OE	RSLP	—	DIVSWEN	ACTIVE
EE1h	REFO1CON1	_	_	_	_	ROSEL3	ROSEL2	ROSEL1	ROSEL0
EE0h	REFO1CON2	RODIV7	RODIV6	RODIV5	RODIV4	RODIV3	RODIV2	RODIV1	RODIV0
EDFh	REFO1CON3	_	RODIV14	RODIV13	RODIV12	RODIV11	RODIV10	RODIV9	RODIV8
EDEh	REF02CON	ON	_	SIDL	OE	RSLP	—	DIVSWEN	ACTIVE
EDDh	REFO2CON1	_	_	_	_	ROSEL3	ROSEL2	ROSEL1	ROSEL0
EDCh	REFO2CON2	RODIV7	RODIV6	RODIV5	RODIV4	RODIV3	RODIV2	RODIV1	RODIV0
EDBh	REFO2CON3	_	RODIV14	RODIV13	RODIV12	RODIV11	RODIV10	RODIV9	RODIV8
EDAh	LCDPS	WFT	BIASMD	LCDA	WA	LP3	LP2	LP1	LP0
ED9h	LCDCON	LCDEN	SLPEN	WERR	CS1	CS0	LMUX2	LMUX1	LMUX0
ED8h	LCDREG	CPEN	_	BIAS2	BIAS1	BIAS0	MODE13	CLKSEL1	CLKSEL0
ED7h	LCDREF	LCDIRE	_	LCDCST2	LCDCST1	LCDCST0	VLCD3PE	VLCD2PE	VLCD1PE
ED6h	LCDRL	LRLAP1	LRLAP0	LRLBP1	LRLBP0		LRLAT2	LRLAT1	LRLAT0
ED5h	LCDSE7	SE63	SE62	SE61	SE60	SE59	SE58	SE57	SE56
ED4h	LCDSE6	SE55	SE54	SE53	SE52	SE51	SE50	SE49	SE48
ED3h	LCDSE5	SE47	SE46	SE45	SE44	SE43	SE42	SE41	SE40
ED2h	LCDSE4	SE39	SE38	S37	SE36	SE35	SE34	SE33	SE32
ED1h	LCDSE3	SE31	SE30	SE29	SE28	SE27	SE26	SE25	SE24
ED0h	LCDSE2	SE23	SE22	SE21	SE20	SE19	SE18	SE17	SE16
Legen	d: = unimpl	emented read as	· '∩'						

8.0 EXTERNAL MEMORY BUS

Note:	The	External	Memory	Bus	is	not
	imple	mented on	64-pin dev	/ices.		

The External Memory Bus (EMB) allows the device to access external memory devices (such as Flash, EPROM or SRAM) as program or data memory. It supports both 8 and 16-Bit Data Width modes, and three address widths of up to 20 bits.

The bus is implemented with 28 pins, multiplexed across four I/O ports. Three ports (PORTD, PORTE and PORTH) are multiplexed with the address/data bus for a total of 20 available lines, while PORTJ is multiplexed with the bus control signals.

A list of the pins and their functions is provided in Table 8-1.

TABLE 8-1: PIC18F97J94 FAMILY EXTERNAL BUS – I/O PORT FUNCTIONS

Name	Port	Bit	External Memory Bus Function
RD0/AD0	PORTD	0	Address Bit 0 or Data Bit 0
RD1/AD1	PORTD	1	Address Bit 1 or Data Bit 1
RD2/AD2	PORTD	2	Address Bit 2 or Data Bit 2
RD3/AD3	PORTD	3	Address Bit 3 or Data Bit 3
RD4/AD4	PORTD	4	Address Bit 4 or Data Bit 4
RD5/AD5	PORTD	5	Address Bit 5 or Data Bit 5
RD6/AD6	PORTD	6	Address Bit 6 or Data Bit 6
RD7/AD7	PORTD	7	Address Bit 7 or Data Bit 7
RE0/AD8	PORTE	0	Address Bit 8 or Data Bit 8
RE1/AD9	PORTE	1	Address Bit 9 or Data Bit 9
RE2/AD10	PORTE	2	Address Bit 10 or Data Bit 10
RE3/AD11	PORTE	3	Address Bit 11 or Data Bit 11
RE4/AD12	PORTE	4	Address Bit 12 or Data Bit 12
RE5/AD13	PORTE	5	Address Bit 13 or Data Bit 13
RE6/AD14	PORTE	6	Address Bit 14 or Data Bit 14
RE7/AD15	PORTE	7	Address Bit 15 or Data Bit 15
RH0/A16	PORTH	0	Address Bit 16
RH1/A17	PORTH	1	Address Bit 17
RH2/A18	PORTH	2	Address Bit 18
RH3/A19	PORTH	3	Address Bit 19
RJ0/ALE	PORTJ	0	Address Latch Enable (ALE) Control Pin
RJ1/OE	PORTJ	1	Output Enable (OE) Control Pin
RJ2/WRL	PORTJ	2	Write Low (WRL) Control Pin
RJ3/WRH	PORTJ	3	Write High (WRH) Control Pin
RJ4/BA0	PORTJ	4	Byte Address Bit 0 (BA0)
RJ5/CE	PORTJ	5	Chip Enable (CE) Control Pin
RJ6/LB	PORTJ	6	Lower Byte Enable (LB) Control Pin
RJ7/UB	PORTJ	7	Upper Byte Enable (UB) Control Pin

Note: For the sake of clarity, only I/O port and external bus assignments are shown here. One or more additional multiplexed features may be available on some pins.

Example 9-3 shows the sequence to do a 16 x 16 unsigned multiplication. Equation 9-1 shows the algorithm that is used. The 32-bit result is stored in four registers (RES3:RES0).

EQUATION 9-1: 16 x 16 UNSIGNED MULTIPLICATION ALGORITHM

RES3:RES0	=	ARG1H:ARG1L · ARG2H:ARG2L
	=	(ARG1H · ARG2H · 2 ¹⁶) +
		(ARG1H · ARG2L · 2 ⁸) +
		(ARG1L · ARG2H · 2 ⁸) +
		(ARG1L · ARG2L)

EXAMPLE 9-3: 16 x 16 UNSIGNED

MULTIPLY ROUTINE

	MOVF	ARG1L, W	
	MULWF	ARG2L	; ARG1L * ARG2L->
			; PRODH:PRODL
	MOVFF	PRODH, RES1	;
	MOVFF	PRODL, RESO	;
;			
	MOVF	ARG1H, W	
	MULWF	ARG2H	; ARG1H * ARG2H->
			; PRODH:PRODL
	MOVFF	PRODH, RES3	i
	MOVFF	PRODL, RES2	i
;			
	MOVF	ARG1L, W	
	MULWF	ARG2H	; ARG1L * ARG2H->
			; PRODH:PRODL
	MOVF	PRODL, W	;
	ADDWF	RES1, F	; Add cross
	MOVF	PRODH, W	; products
	ADDWFC	RES2, F	;
	CLRF	WREG	;
	ADDWFC	RES3, F	;
;			
	MOVF	ARG1H, W	;
	MULWF	ARG2L	; ARG1H * ARG2L->
			; PRODH:PRODL
	MOVF	PRODL, W	;
	ADDWF	RES1, F	; Add cross
	MOVF	PRODH, W	; products
	ADDWFC	RES2, F	;
	CLRF	WREG	;
	ADDWFC	RES3, F	;
;	MOVF MULWF ADDWF ADDWF ADDWFC CLRF ADDWFC	ARG1H, W ARG2L PRODL, W RES1, F PRODH, W RES2, F WREG RES3, F	; ; ARG1H * ARG2L-> ; PRODH:PRODL ; ; Add cross ; products ; ; ;

Example 9-4 shows the sequence to do a 16 x 16 signed multiply. Equation 9-2 shows the algorithm used. The 32-bit result is stored in four registers (RES3:RES0). To account for the sign bits of the arguments, the MSb for each argument pair is tested and the appropriate subtractions are done.

EQUATION 9-2: 16 x 16 SIGNED MULTIPLICATION ALGORITHM

RES3:RES0=	ARG1H:ARG1L · ARG2H:ARG2L
=	(ARG1H · ARG2H · 2 ¹⁶) +
	(ARG1H · ARG2L · 2 ⁸) +
	(ARG1L · ARG2H · 2 ⁸) +
	(ARG1L · ARG2L) +
	(-1 · ARG2H<7> · ARG1H:ARG1L · 2 ¹⁶) +
	(-1 · ARG1H<7> · ARG2H:ARG2L · 2 ¹⁶)

EXAMPLE 9-4: 16 x 16 SIGNED MULTIPLY ROUTINE

	MOVF	ARG1L, W		
	MULWF	ARG2L	;	ARG1L * ARG2L ->
			;	PRODH:PRODL
	MOVFF	PRODH, RES1	;	
	MOVFF	PRODL, RESO	;	
;				
	MOVF	ARG1H, W		
	MULWF	ARG2H	;	ARG1H * ARG2H ->
			;	PRODH:PRODL
	MOVFF	PRODH, RES3	;	
	MOAF.F.	PRODL, RES2	;	
i	MOVE	ADC11 W		
		ARGIL, W		
	MOLWF	ARGZH	΄.	ARGIL " ARGZH ->
	MOVE	DRODI W	;	PRODE
	ADDWF	RESI F	;	Add cross
	MOVE	PRODH W	;	products
	ADDWFC	RES2. F	;	produces
	CLRF	WREG	;	
	ADDWFC	RES3. F	;	
;				
	MOVF	ARG1H, W	;	
	MULWF	ARG2L	;	ARG1H * ARG2L ->
			;	PRODH:PRODL
	MOVF	PRODL, W	;	
	ADDWF	RES1, F	;	Add cross
	MOVF	PRODH, W	;	products
	ADDWFC	RES2, F	;	
	CLRF	WREG	;	
	ADDWFC	RES3, F	;	
;				
	BTFSS	ARG2H, 7	;	ARG2H:ARG2L neg?
	BRA SIC	GN_ARG1	;	no, check ARG1
	MOVF	ARG1L, W	;	
	SUBWF	RES2	;	
	MOVF	ARG1H, W	;	
~-	SUBWFB	RES3	;	
SI	GN_ARGI			
	BIFSS	ARGIH, /	΄.	ARGIH·ARGIL neg?
	BKA	ADC21 W	΄.	no, done
	CUDWE	ARGZL, W	;	
	MOVE	ADCOU W		
	SUBWEB	RES3	'	
;	SODALD			
CO	NT CODE			
	:			



REGISTER 11-5: RPORn_n: REMAPPED PERIPHERAL OUTPUT REGISTER n (FUNCTION MAPS TO PIN)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
RPORn_3	RPORn_2	RPORn_1	RPORn_0	RPmR_3	RPmR_2	RPmR_1	RPmR_0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read a	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-4 **RPORn_<3:0>:** RPn peripheral output function mapping

bit 3-0 **RPmR<3:0>:** RPm peripheral output function mapping

Note 1: Register values can only be changed if IOLOCK = 0.

13.3 LCD Clock Source Selection

The LCD driver module has three possible clock sources:

- FRC/8192
- SOSC Clock/32
- LPRC/32

The first clock source is the 8 MHz Fast Internal RC (FRC) Oscillator divided by 8,192. This divider ratio is chosen to provide about 1 kHz output. The divider is not programmable. Instead, the LCD prescaler bits, LCDPS<3:0>, are used to set the LCD frame clock rate.

The second clock source is the SOSC Oscillator/32. This also outputs about 1 kHz when a 32.768 kHz crystal is used with the SOSC Oscillator. To use the SOSC Oscillator as a clock source, set the SOSCEN (T1CON<3>) bit.

The third clock source is a 31.25 kHz internal LPRC Oscillator/32 that provides approximately 1 kHz output.

The second and third clock sources may be used to continue running the LCD while the processor is in Sleep.

These clock sources are selected through the bits, CS<1:0> (LCDCON<4:3>).

13.3.1 LCD PRESCALER

A 16-bit counter is available as a prescaler for the LCD clock. The prescaler is not directly readable or writable. Its value is set by the LP<3:0> bits (LCDPS<3:0>) that determine the prescaler assignment and prescale ratio.

Selectable prescale values are from 1:1 through 1:16, in increments of one.



FIGURE 13-2: LCD CLOCK GENERATION





15.6 Timer1/3/5 Interrupt

The TMRx register pair (TMRxH:TMRxL) increments from 0000h to FFFFh and overflows to 0000h. The Timerx interrupt, if enabled, is generated on overflow and is latched in the interrupt flag bit, TMRxIF. Table 15-3 gives each module's flag bit.

TABLE 15-3: TIMER1/3/5 INTERRUPT FLAG BITS

Timer Module	Flag Bit
1	PIR1<0>
3	PIR2<1>
5	PIR5<1>

This interrupt can be enabled or disabled by setting or clearing the TMRxIE bit, respectively. Table 15-4 gives each module's enable bit.

TABLE 15-4: TIMER1/3/5 INTERRUPT ENABLE BITS

Timer Module	Flag Bit
1	PIE1<0>
3	PIE2<1>
5	PIE5<1>

15.7 Resetting Timer1/3/5 Using the ECCP Special Event Trigger

If the ECCP modules are configured to use Timerx and to generate a Special Event Trigger in Compare mode (CCPxM<3:0> = 1011), this signal will reset Timerx. The trigger from ECCP2 will also start an A/D conversion if the A/D module is enabled (For more information, see **Section 18.3.4 "Special Event Trigger"**.)

The module must be configured as either a timer or synchronous counter to take advantage of this feature. When used this way, the CCPRxH:CCPRxL register pair effectively becomes a Period register for Timerx.

If Timerx is running in Asynchronous Counter mode, the Reset operation may not work.

In the event that a write to Timerx coincides with a Special Event Trigger from an ECCP module, the write will take precedence.

Note:	The Special Event Triggers from the
	ECCPx module will only clear the TMR3
	register's content, but not set the TMR3IF
	interrupt flag bit (PIR1<0>).

Note: The CCP and ECCP modules use Timers, 1 through 8, for some modes. The assignment of a particular timer to a CCP/ECCP module is determined by the Timer to CCP enable bits in the CCPTMRSx registers. For more details, see Register 18-2, Register 18-3 and Register 19-2

17.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

The key features of the Real-Time Clock and Calendar (RTCC) module are:

- Hardware Real-Time Clock and Calendar (RTCC)
- Provides hours, minutes and seconds using 24- hour format
- · Visibility of one-half second period
- Provides calendar weekday, date, month and year
- Alarm configurable for half a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week or one month
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat chime
- · Year 2000 to 2099 leap year correction
- BCD format for smaller software overhead
- · Optimized for long term battery operation
- · Fractional second synchronization

- Multiple clock sources
 - SOSC
 - LPRC
 - 50 Hz
 - 60 Hz
- User calibration of the 32.768 kHz clock crystal frequency with periodic auto-adjust
- Calibration to within ±2.64 seconds error per month
- · Calibrates up to 260 ppm of crystal error

The RTCC module is intended for applications where accurate time must be maintained for an extended period with minimum to no intervention from the CPU. The module is optimized for low-power usage in order to provide extended battery life, while keeping track of time.

The module is a 100-year clock and calendar with automatic leap year detection. The range of the clock is from 00:00:00 (midnight) on January 1, 2000 to 23:59:59 on December 31, 2099.

Hours are measured in 24-hour (military time) format. The clock provides a granularity of one second with half-second visibility to the user.



FIGURE 17-1: RTCC BLOCK DIAGRAM

17.1.4 RTCEN BIT WRITE

RTCWREN (RTCCON1<5>) must be set before a write to RTCEN can take place. Any write to the RTCEN bit, while RTCWREN = 0, will be ignored.

Like the RTCEN bit, the RTCVALH and RTCVALL registers can only be written to when RTCWREN = 1. A write to these registers, while RTCWREN = 0, will be ignored.

FIGURE 17-2: TIMER DIGIT FORMAT

17.2 Operation

17.2.1 REGISTER INTERFACE

The register interface for the RTCC and alarm values is implemented using the Binary Coded Decimal (BCD) format. This simplifies the firmware when using the module, as each of the digits is contained within its own 4-bit value (see Figure 17-2 and Figure 17-3).



FIGURE 17-3: ALARM DIGIT FORMAT



20.0 MASTER SYNCHRONOUS SERIAL PORT (MSSP) MODULE

20.1 Master SSP (MSSP) Module Overview

The Master Synchronous Serial Port (MSSP) module is a serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices may be serial EEPROMs, shift registers, display drivers, A/D Converters, etc. The MSSP module can operate in one of two modes:

- Serial Peripheral Interface (SPI)
- Inter-Integrated Circuit[™] (I²C)
 - Full Master mode
 - Slave mode (with general address call)

The I²C interface supports the following modes in hardware:

- Master mode
- Multi-Master mode
- Slave mode with 5-bit and 7-bit address masking (with address masking for both 10-bit and 7-bit addressing)

All members of the PIC18FXXJ94 have two MSSP modules, designated as MSSP1 and MSSP2. Each module operates independently of the other.

Note: Throughout this section, generic references to an MSSP module in any of its operating modes may be interpreted as being equally applicable to MSSP1 or MSSP2. Register names and module I/O signals use the generic designator 'x' to indicate the use of a numeral to distinguish a particular module when required. Control bit names are not individuated.

20.2 Control Registers

Each MSSP module has four associated control registers. These include a STATUS register (SSPxSTAT) and three control registers (SSPxCON1, SSPxCON2, and SSPxCON3). The use of these registers and their individual Configuration bits differ significantly depending on whether the MSSP module is operated in SPI or I^2C mode.

Additional details are provided under the individual sections. On all PIC18F97J94 family devices, the SPI DMA capability can only be used in conjunction with MSSP1. The SPI DMA feature is described in **Section 20.4 "SPI DMA Module"**.

Note: In devices with more than one MSSP module, it is very important to pay close attention to SSPxCON register names. SSP1CON1 and SSP1CON2 control different operational aspects of the same module, while SSP1CON1 and SSP2CON1 control the same features for two different modules.

Note: The SSPxBUF register cannot be used with read-modify-write instructions, such as BCF, COMF, etc. To avoid lost data in Master mode, a read of the SSPxBUF must be per-

formed to clear the Buffer Full (BF) detect bit (SSPSTAT<0>) between each transmission.

20.3.4 ENABLING SPI I/O

To enable the serial port, the peripheral must first be mapped to I/O pins using the PPS-Lite feature. To enable the SPI peripheral, the MSSPx Enable bit, SSPEN (SSPxCON1<5>) must be set. To reset or reconfigure SPI mode, clear the SSPEN bit, re-initialize the SSPxCON registers and then set the SSPEN bit. This configures the SDIx, SDOx, SCKx and SSx pins as serial port pins. For the pins to behave as the serial port function, some must have their data direction bits (in the TRIS register) appropriately programmed as follows:

- SDIx is automatically controlled by the SPI module
- SDOx must have the TRIS bit cleared for the corresponding RPn pin.
- SCKx (Master mode) must have the TRIS bit cleared for the corresponding RPn pin
- SCKx (Slave mode) must have the TRIS bit set for the corresponding RPn pin
- SSx must have the TRIS bit set for the corresponding RPn pin.

Any serial port function that is not desired may be overridden by programming the corresponding Data Direction (TRIS) register to the opposite value.

FIGURE 20-2: SPI MASTER/SLAVE CONNECTION

20.3.5 TYPICAL CONNECTION

Figure 20-2 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCKx signal. Data is shifted out of both shift registers on their programmed clock edge and latched on the opposite edge of the clock. Both processors should be programmed to the same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application software. This leads to three scenarios for data transmission:

- · Master sends data Slave sends dummy data
- · Master sends data Slave sends data
- · Master sends dummy data Slave sends data



R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	EXTSAM	PUMPEN	SAMC4	SAMC3	SAMC2	SAMC1	SAMC0
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable I	oit	U = Unimplen	nented bit, read	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown
bit 7	ADRC: A/D C	onversion Cloc	k Source bit				
	1 = RC Clock	ĸ					
	0 = Clock der	rived from syste	em clock				
bit 6	EXTSAM: Ex	tended Samplir	ng Time bit				
	1 = A/D is sti	ll sampling afte	r SAMP = 0				
	0 = A/D is fin	ished sampling					
bit 5	PUMPEN: Ch	arge Pump En	able bit				
	1 = Charge p	oump for switch	es is enabled				
	0 = Charge p	oump for switch	es is disabled				
bit 4-0	SAMC<4:0>:	Auto-Sample T	ime Select bit	S			
	11111 = 31 T	AD					
	•••	_					
	00001 = 1 IAI						

REGISTER 22-8: ADCON3H: A/D CONTROL REGISTER 3 HIGH

REGISTER 22-9: ADCON3L: A/D CONTROL REGISTER 3 LOW

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| ADCS7 | ADCS6 | ADCS5 | ADCS4 | ADCS3 | ADCS2 | ADCS1 | ADCS0 |
| bit 7 | | | | | | | bit 0 |

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 ADCS<7:0>: A/D Conversion Clock Select bits ((ADCS<7:0> + 1) 2/Fosc) = TAD

11111111 • • • = Reserved 01000000 00111111 = 64 · 2/Fosc = TAD • • • 00000001 = 2 · 2/Fosc = TAD 00000000 = 2/Fosc = TAD

REGISTER 22-13: ADCHS0L: A/D SAMPLE SELECT REGISTER 0 LOW

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CH0NA2	CH0NA1	CH0NA0	CH0SA4	CH0SA3	CH0SA2	CH0SA1	CH0SA0
bit 7							bit 0
Legend:							
R = Readabl	le bit	W = Writable	bit	U = Unimple	mented bit, rea	d as '0'	
-n = Value at	t POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unk	nown
bit 7-5	CH0NA<2:0	>: Sample A Ch	annel 0 Negat	ve Input Selec	t bits		
	1xx = Unim	plemented	anner e rregat				
	011 = Unim	plemented					
	010 = AN1						
	001 = Unim	plemented					
	000 = VREF-	-/AVss					
bit 4-0	CH0SA<4:0	>: Sample A Ch	annel 0 Positiv	e Input Select	bits		
	11111 = V BA	AT/2 ⁽¹⁾					
	11110 = AV C	(1) _{DC}					
	11101 = AV s	_{SS} (1)					
	11100 = Bar	nd gap reference	e (VBG) ⁽¹⁾				
	11011 = V BG	∋/2 ⁽¹⁾					
	11010 = V BC	6 ⁽¹⁾					
	11001 = CTN	MU					
	11000 = CIN	MU temperature	sensor input (does not requi	re ADCIMUEN	N1H<0> to be s	et)
	10111 = AN2	23(*)					
	10110 = AN2	22 ⁽⁻⁾ 01(2)					
	10101 - AN2	2 (2)					
	$10011 = \Delta N^2$	19					
	$10010 = AN^{2}$	18					
	10001 = AN	17					
	10000 = AN ²	16					
	01111 = AN ²	15					
	01110 = AN ²	14					
	01101 = AN ²	13					
	01100 = AN ²	12					
	01011 = AN	11					
	01010 = AN ²	10					
	01001 = ANS	9					
	01000 = AN8	8					
	00111 = AN	/ c					
	00110 - ANG	5					
	00101 - AN	1					
	00011 = AN	3					
	00010 = AN2	2					
	00001 = AN	1					
	00000 = AN(D					

- Note 1: These input channels do not have corresponding memory mapped result buffers.
 - 2: These channels are implemented in 80-pin and 100-pin devices only.



For the 10-bit transfer function (when 10-bit resolution is available):

- The first code transition occurs when the input voltage is ((VR+) (VR-))/1024 or 1.0 LSb.
- The '00 0000 0001' code is centered at VR- + (1.5 * (((VR+) (VR-)) / 1024).
- The '10 0000 0000' code is centered at VREFL + (512.5 * (((VR+) (VR-)) /1024).
- An input voltage less than VR- + (((VR-) (VR-)) / 1024) converts as '00 0000 0000'.
- An input voltage greater than (VR-) + ((1023 (VR+)) (VR-))/1024) converts as '11 1111 1111'.

REGISTER 23-2: CMST	AT: COMPARATOR	STATUS REGISTER
---------------------	----------------	-----------------

U-0	U-0	U-0	U-0	U-0	R-x	R-x	R-x
	—	_	—	—	C3OUT	C2OUT	C1OUT
bit 7							bit 0
Lonondi							

Legena.			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	d as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-3 Unimplemented: Read as '0'

bit 2-0	C3OUT:C1OUT: Comparator x Status bits
	If CPOL (CMxCON<5>)= 0 (non-inverted polarity):

1 = Comparator x's VIN+ > VIN-

0 = Comparator x's VIN+ < VIN-

CPOL = 1 (inverted polarity):

1 = Comparator x's VIN+ < VIN-

0 = Comparator x's VIN + > VIN

23.2 Comparator Operation

A single comparator is shown in Figure 23-2, along with the relationship between the analog input levels and the digital output. When the analog input at VIN+ is less than the analog input, VIN-, the output of the comparator is a digital low level. When the analog input at VIN+ is greater than the analog input, VIN-, the output of the comparator is a digital high level. The shaded areas of the output of the comparator in Figure 23-2 represent the uncertainty due to input offsets and response time.

FIGURE 23-2: SINGLE COMPARATOR



23.3 Comparator Response Time

Response time is the minimum time, after selecting a new reference voltage or input source, before the comparator output has a valid level. The response time of the comparator differs from the settling time of the voltage reference. Therefore, both of these times must be considered when determining the total response to a comparator input change. Otherwise, the maximum delay of the comparators should be used (see **Section 30.0 "Electrical Specifications"**).

23.4 Analog Input Connection Considerations

A simplified circuit for an analog input is shown in Figure 23-3. Since the analog pins are connected to a digital output, they have reverse biased diodes to VDD and VSs. The analog input, therefore, must be between VSs and VDD. If the input voltage deviates from this range by more than 0.6V in either direction, one of the diodes is forward biased and a latch-up condition may occur.

A maximum source impedance of $10 \text{ k}\Omega$ is recommended for the analog sources. Any external component connected to an analog input pin, such as a capacitor or a Zener diode, should have very little leakage current.

REGISTER 24-2: CVRCONL: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER LOW

R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0
CVREN	CVROE	CVRPSS1	CVRPSS0	—	—	—	CVRNSS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read	l as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7	CVREN: Comparator Voltage Reference Enable bit
	1 = CVREF circuit is powered on
	0 = CVREF circuit is powered down
bit 6	CVROE: Comparator VREF Output Enable bit
	1 = CVREF voltage level is output on CVREF pin
	0 = CVREF voltage level is disconnected from CVREF pin
bit 5-4	CVRPSS<1:0>: Comparator VREF Positive Source (VPOSSRC) Selection bits
	11 = Reserved, do not use. Positive source is floating
	10 = VBG (Band gap)
	$01 = \mathbf{V} \mathbf{R} \mathbf{F} \mathbf{F}$
bit 3-1	Unimplemented: Read as '0'
bit 0	CVRNSS: Comparator VREF Negative Source (VNEGSRC) Selection bit
	01 = VREF-
	00 = AVss

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



The USB Specification limits the power taken from the bus. Each device is ensured 100 mA at approximately 5V (one unit load). Additional power may be requested, up to a maximum of 500 mA.

Note that power above one unit load is a request and the host or hub is not obligated to provide the extra current. Thus, a device capable of consuming more than one unit load must be able to maintain a low-power configuration of a one unit load or less, if necessary.

The USB Specification also defines a Suspend mode. In this situation, current must be limited to 500 μ A, averaged over one second. A device must enter a suspend state after 3 ms of inactivity (i.e., no SOF tokens for 3 ms). A device entering Suspend mode must drop current consumption within 10 ms after suspend. Likewise, when signaling a wake-up, the device must signal a wake-up within 10 ms of drawing current above the suspend limit.

27.9.5 ENUMERATION

When the device is initially attached to the bus, the host enters an enumeration process in an attempt to identify the device. Essentially, the host interrogates the device, gathering information, such as power consumption, data rates and sizes, protocol and other descriptive information; descriptors contain this information. A typical enumeration process would be as follows:

- 1. USB Reset Reset the device. Thus, the device is not configured and does not have an address (Address 0).
- 2. Get Device Descriptor The host requests a small portion of the device descriptor.
- 3. USB Reset Reset the device again.
- 4. Set Address The host assigns an address to the device.
- 5. Get Device Descriptor The host retrieves the device descriptor, gathering info, such as manufacturer, type of device, maximum control packet size.
- 6. Get configuration descriptors.
- 7. Get any other descriptors.
- 8. Set a configuration.

The exact enumeration process depends on the host.

27.9.6 DESCRIPTORS

There are eight different standard descriptor types, of which, five are most important for this device.

27.9.6.1 Device Descriptor

The device descriptor provides general information, such as manufacturer, product number, serial number, the class of the device and the number of configurations. There is only one device descriptor.

27.9.6.2 Configuration Descriptor

The configuration descriptor provides information on the power requirements of the device and how many different interfaces are supported when in this configuration. There may be more than one configuration for a device (i.e., low-power and high-power configurations).

27.9.6.3 Interface Descriptor

The interface descriptor details the number of endpoints used in this interface, as well as the class of the interface. There may be more than one interface for a configuration.

27.9.6.4 Endpoint Descriptor

The endpoint descriptor identifies the transfer type (**Section 27.9.3 "Transfers"**) and direction, and some other specifics for the endpoint. There may be many endpoints in a device and endpoints may be shared in different configurations.

27.9.6.5 String Descriptor

Many of the previous descriptors reference one or more string descriptors. String descriptors provide human readable information about the layer (Section 27.9.1 "Layered Framework") they describe. Often these strings show up in the host to help the user identify the device. String descriptors are generally optional to save memory and are encoded in a unicode format.

27.9.7 BUS SPEED

Each USB device must indicate its bus presence and speed to the host. This is accomplished through a $1.5 \text{ k}\Omega$ resistor, which is connected to the bus at the time of the attachment event.

Depending on the speed of the device, the resistor either pulls up the D+ or D- line to 3.3V. For a lowspeed device, the pull-up resistor is connected to the D- line. For a full-speed device, the pull-up resistor is connected to the D+ line.

27.9.8 CLASS SPECIFICATIONS AND DRIVERS

USB specifications include class specifications, which operating system vendors optionally support. Examples of classes include: Audio, Mass Storage, Communications and Human Interface (HID). In most cases, a driver is required at the host side to 'talk' to the USB device. In custom applications, a driver may need to be developed. Fortunately, drivers are available for most common host systems for the most common classes of devices. Thus, these drivers can be reused.

U-1	U-1	U-1	U-1	R/WO-1	R/WO-1	R/WO-1	R/WO-1
_	_	_	—	MSSPMSK1	MSSPMSK2	LS48MHZ	IOL1WAY
bit 7							bit 0
Legend:		P = Programmable bit		WO = Write-Once bit			
R = Readable bit		W = Writable	bit	U = Unimplemented bit			
-n = Value at POR		'1' = Bit is se	t	'0' = Bit is cleared		x = Bit is unknown	
bit 7-4	Unimplemented: Program the corresponding Flash Configuration bit to '1'						
bit 3	it 3 MSSPMSK1: MSSP1 7-Bit Address Masking Mode Enable bit						
	1 = 7-Bit Address Masking mode enable						
	0 = 5-Bit Address Masking mode enable						
bit 2	MSSPMSK	2: MSSP2 7-E	it Address Ma	sking Mode Ena	ble bit		
	1 = 7-Bit Address Masking mode enable						
	0 = 5-Bit Address Masking mode enable						
bit 1	LS48MHZ: Low-Speed USB Clock Selection bit						
	1 = 48 MHz system clock is expected; divide-by-8 generates low-speed USB clock						
	0 = 24 MHz system clock is expected; divide-by-4 generates low-speed USB clock						
bit 0	IOL1WAY: IOLOCK Bit One-Way Set Enable bit						
	1 = The IOLOCK bit can only be set once (provided an unlocking sequence is executed); this prevents any possible future RP register changes						

REGISTER 28-9: CONFIG5H: CONFIGURATION REGISTER 5 HIGH (BYTE ADDRESS 300009h)

any _b iture RP register changes

0 = The IOLOCK bit can be set and cleared as needed (provided an unlocking sequence is executed)